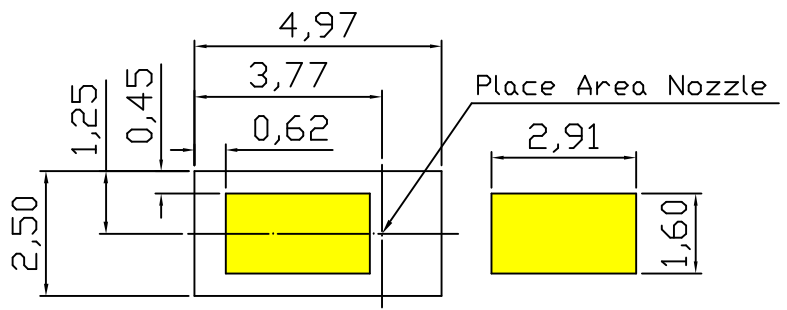


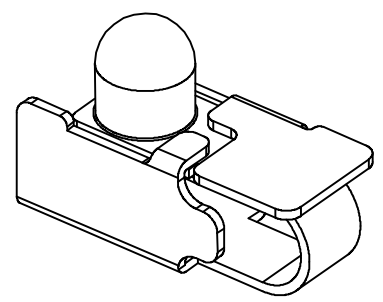
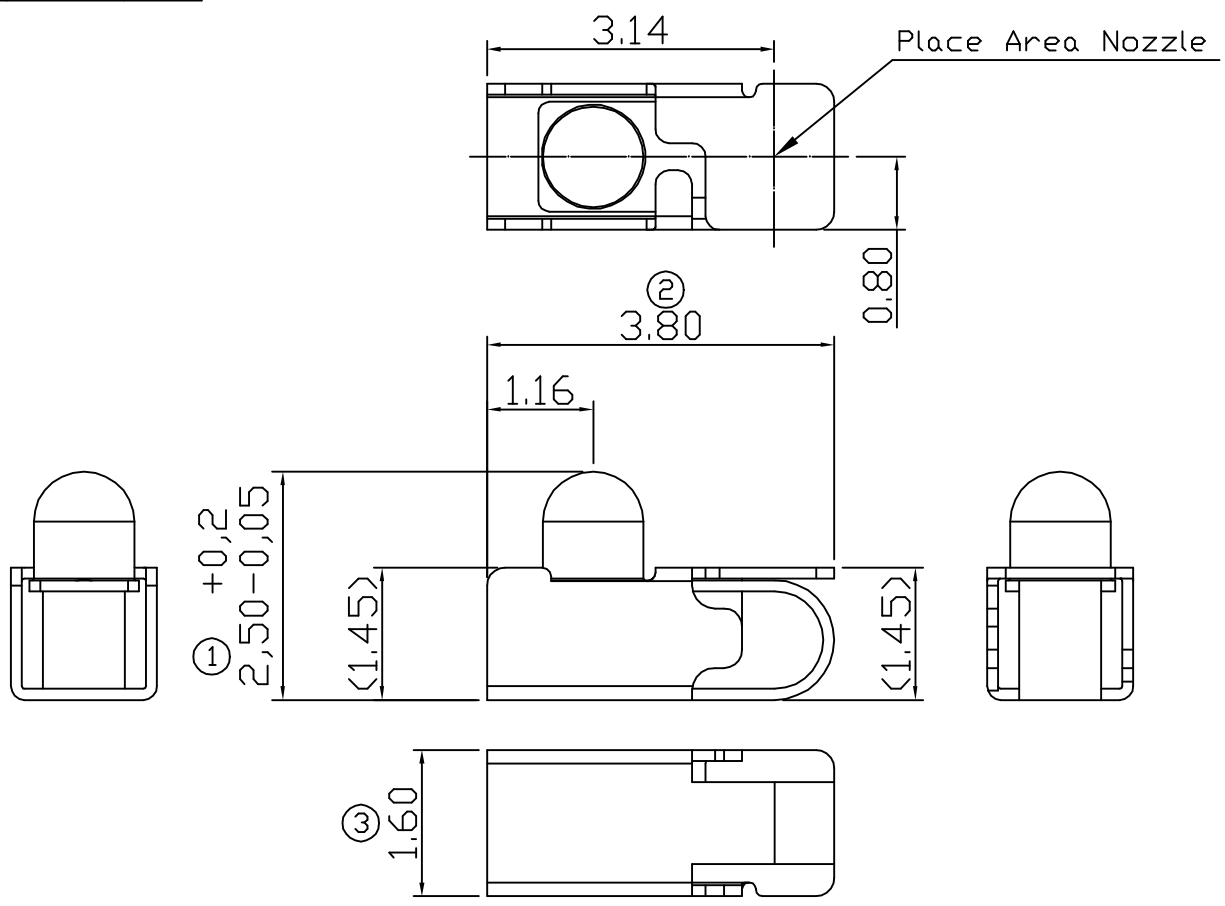
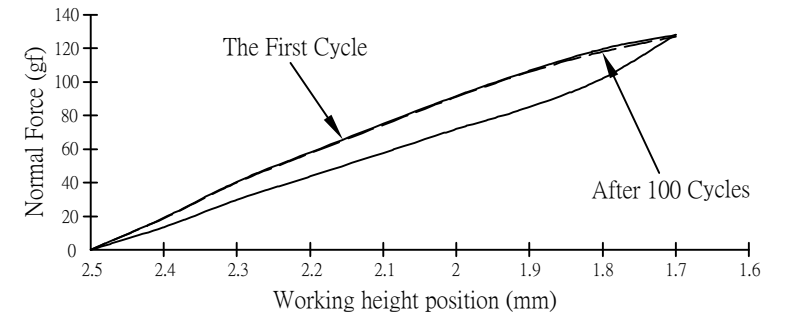
00 11/25-'13

A
B
C
D
E
F



RECOMMENDED SOLDERING PCB LAYOUT

TOLERANCE(.XX±0.05)



- Note:
1. Material: Beryllium Copper Thickness 0.12mm
 2. Electroplate:
 - Au >1u' on contact area
 - Au >1u' on solder area
 - Nickel underplating over all
 3. Electrical Characteristics:
 - 3-1 Current Voltage: 12V
 - 3-2 Current Rate: 3A
 - 3-3 Contact Resistance: Normal Compression <30mΩ
 4. Working Height of Application: 1.60~2.00 mm
 5. Spring Force Tolerance is ±20gf
 6. Operating Temperature: -20℃~+85℃

00	11/25-'13	Design creation		
REV	Date	Description		
DRAFT	Bill Chang	DATE	11/25-'13	RoHS Compatible
CHECKER	Jacky Lin	DATE	11/25-'13	
APPROVAL	Jacky Lin	DATE	11/25-'13	SHEET 1-2
		SCALE	Not to scale	UNIT mm

TOLERANCE/CLASS			
RANGE(mm)	1	2	3
≤30	±0.10	0.15	0.20
30<- ≤120	±0.15	0.20	0.30
120<- ≤300	±0.20	0.30	0.50
300<	±0.30	0.50	0.80
ANGLES	±2.5°		

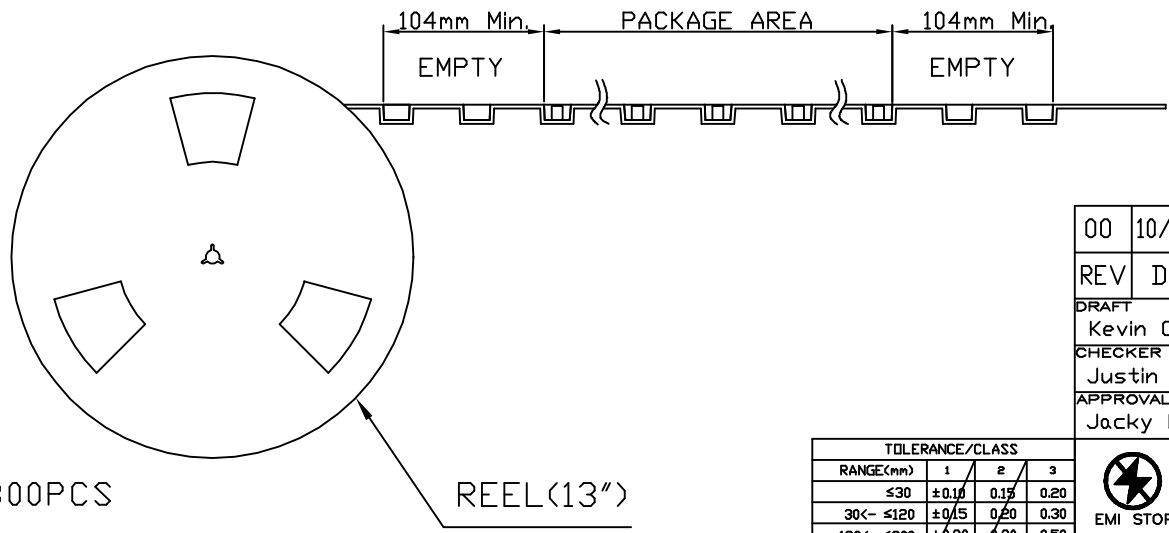
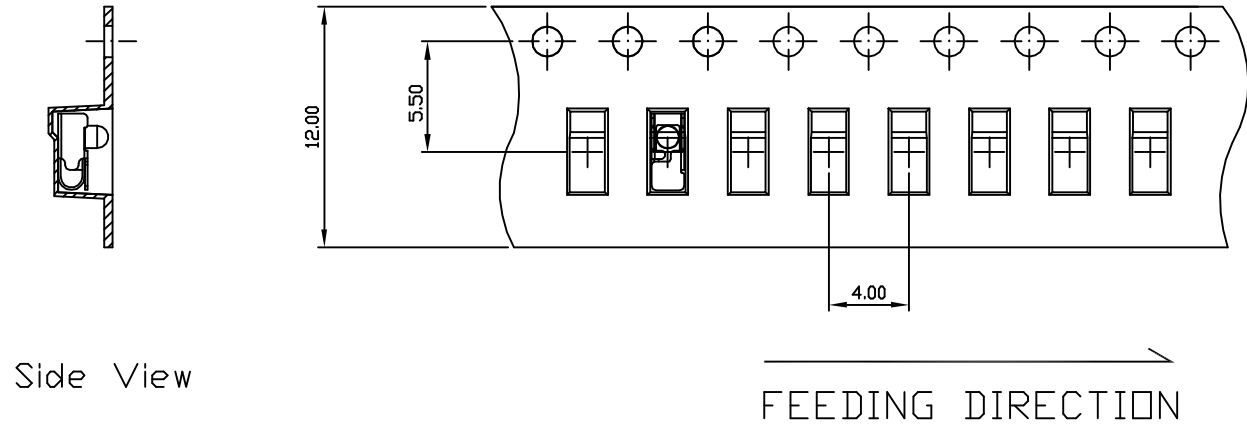
EMI STOP CORP.

EMI STOP

EMISTOP QQ-25A1G	CUS P/N
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1 2 3 4 5 6 7 8

A
B
C
D
E
F



Package Information:
 1.Quantity Per Reel: 5300PCS
 2.REEL: 13"X 12 mm

TOLERANCE/CLASS			
RANGE(mm)	1	2	3
≤30	±0.10	0.15	0.20
30<- ≤120	±0.15	0.20	0.30
120<- ≤300	±0.20	0.30	0.50
300<	±0.30	0.50	0.80
ANGLES	±2.5°		

00	10/30-'19'	Design creation			
REV	Date	Description			
DRAFT	Kevin Chen	DATE	10/30-'19	RoHS Compatible	
CHECKER	Justin Wu	DATE	10/30-'19		
APPROVAL	Jacky Lin	DATE	10/30-'19	SHEET	2-2
		SCALE	Not to scale	UNIT	mm

 **EMI STOP CORP.**

EMISTOP
 QQ-25A1G

CUS P/N